Special Issue

Towards a Digital Built Environment: The Role of Digital Engineering, IoT and Artificial Intelligence

Message from the Guest Editors

This proposed and pioneering Special Issue is the first to provide a platform for construction researchers who seek to showcase the emergent findings from their research not only on the roles of DE, IoT, and AI, but also on their integration, in relation to disruption in the construction industry's ways of working. The Special Issue particularly invites papers that provide accounts of real-life DE, IoT, and AI case studies. Other themes sought for the Special Issue include exploring the emerging methodologies of DE, IoT, and AI integration, and determining how DE, IoT, and AI can benefit the construction industry. **Keywords**

- built environment
- construction industry
- Industry 4.0
- digitalization
- building information modeling
- innovation diffusion
- digital engineering
- IoT
- Artificial Intelligence

Guest Editors

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Deadline for manuscript submissions

closed (10 January 2022)



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About the Journal

Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

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